Recruiting Activities for Global Talents by Electronics Industry Promotion Office, SIPO

2019/8/23
Electronics Industry Promotion Office, SIPO is established by the Ministry of Economic Affairs, MOEA, R.O.C. in 2002.

**Mission**

To function as a promotion office for Semiconductor and Smart Electronics industry in Taiwan.

**Services**

- Recruiting activities for global talents
- To engage Taiwanese semiconductor/Smart electronics companies with global companies and foster business opportunities.
Recruiting Activities for Semiconductor, Smart Electronics, AI Talents

6 companies, 19 job openings
### 3 job openings from Global Unichip Corporation (創意電子)

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<thead>
<tr>
<th>Categories</th>
<th>Company</th>
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</table>
| IC Design    | 創意電子 Global Unichip Corporation | DFT Engineer (MBIST / Scan)                   | 1. Involve in ensure total silicon quality both in design phase.                 | Taiwan       | 5 years above | 1. Familiar with Verilog / RTL / STA / Simulation … other verification flow  
2. Proficient in programming skill and UNIX shell  
3. MBIST / Scan diagnosis experience and ATE test debug experience.  
4. System level MBIST planning / Knowledge of boundary scan  
6. EDA development for logic design flow and DFT flow  
7. Experience in IC design file, familiar DFT of MBIST/SCAN skills | Permanent     |
|              |                        | Digital IP Design Engineer                    | 1. DDR/LPDDR/GDDR/HBM logic design and verification                            | Taiwan       | 3 years above | 1. Over 3-year digital design experiences  
2. Familiar with DDR/LPDDR/HBM/SerDes or DSP is plus  
3. Familiar with digital IC front-end design flow such as Verilog RTL design, Synopsys Design Compiler, LEC Spyglass, PrimeTime STA | Permanent     |
|              |                        | DDR PHY Design Engineer                       | IO circuit design and layout reviewing, DDR PHY design and verification         | Taiwan       | 5 years above | NA                                                                                                                                                    | Permanent     |

Job updated on 2019/07/05
## 7 job openings from Realtek Semiconductor Corp. (瑞昱半導體) (1/2)

**Job updated on 2019/07/05**

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| IC Design  | Realtek Semiconductor Corp. | Senior Software Design Engineer | 1. Wireless AP / Embedded System software development  
2. Router protocol / Wi-Fi related development  
3. Embedded system development  
4. FPGA Board for high speed signal integration and verification  
5. Customer Support | Hsinchu, Taiwan | 5 years | 1. MS Degree or above in Computer, Electronic, Electrical or Networking Engineering.  
2. Familiar with C/C++ and Linux system.  
3. Familiar with networking / embedded system development and have the experience in driver-related development.  
4. Wi-Fi development experience will be a plus  
5. Good communication and team working skills. | Permanent |
| IC Design  | Realtek Semiconductor Corp. | Senior Digital IC Design Engineer | 1. Verilog RTL design implementation  
2. SoC System FPGA verification and debug  
3. Synthesis, LEC, STA, DFT, and SoC integration  
4. This includes but not limited to, logic design, RTL coding, test bench writing, RTL/gate-level simulation/verification and code coverage | Hsinchu, Taiwan | 5 years | 1. MS Degree or above in EE or Computer Engineering  
2. Good knowledge on digital VLSI design  
3. Good knowledge and experience on Verilog RTL design, Verilog simulation, logic synthesis, STA, LEC and FPGA verification  
4. Familiar with HDL design and SoC system structure  
5. Strong analytical and problem solving skills  
6. Good verbal and communication skills | Permanent |
| IC Design  | Realtek Semiconductor Corp. | Senior Analog IC Design Engineer | 1. Analog Circuits design for drivers and transceiver  
2. Analog IP development  
3. Power Management design | Hsinchu, Taiwan | 5 years | 1. MS Degree or above in EE or Computer Engineering.  
3. Experience in any of Serdes, PCIe, USB, SATA, HDMI, Class-D Amplifier, Code, RF, PA, VCO, ADC, PLL, Transceiver, Transmitter, Receiver will be a plus.  
4. Strong analytical and problem solving skills  
5. Good verbal and communication skills | Permanent |
| IC Design  | Realtek Semiconductor Corp. | Senior Design Verification Engineer | 1. Responsibility for test plans, test bench documentation and implementation.  
2. Use System Verilog language, SVA and UVM methodology for block and top level verification.  
3. Apply formal property checking/formal verification methodologies  
4. Understanding of the fundamentals of computer architecture | Hsinchu, Taiwan | 5 years | 1. MS Degree or above in Electrical, Electronics or Computer Engineering  
2. Familiar with System Verilog, SVA, Perl, CRV, VMM/UVM Methodology  
3. Familiar with EDA Tools such as Formal Verification Tool (Cadence Jasper, Synopsys Magellan)  
4. Good analytical problems solving skills  
5. Good C/C++ Programming skills  
6. Good verbal and written communication skills  
7. Self-motivated and possess team working skills | Permanent |
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| IC Design     | Realtek Semiconductor Corp. | Senior System Architecture Engineer | 1. Developing SoC design for network platform, especially SW/HW integration design  
2. Architecture and specification design for network SOC (Wi-Fi AP Router experience is better)  
3. Coordination of debug for IP issue (e.g. USB/PCIe/Memory System/...), especially system integration issue (e.g. system crack)  
4. Acting as a technical and project lead role of those IPs and overall architecture | Hsinchu, Taiwan | 5 years | 1. MS degree or above in Computer, Electronics or Networking engineering  
2. Ever work in IC design house with 5 years of experience  
3. Strong knowledge and experience in Embedded System development  
4. Good Knowledge for ARM or MIPS processors  
5. Basic Knowledge for Network architecture (PHY layer, Data link layer, TCP/IP layer), Switch experience is better  
6. Basic Knowledge for Linux kernel  
7. Ability to work with other engineers or to lead a team of engineers for large-scale designs | Permanent       |
|               |                          | Senior Algorithm Development Engineer | 1. Wired or wireless communication system transceiver architecture or algorithm design.  
2. RF/Analog frontend & baseband system specification design  
3. Channel and impairment modeling  
4. Baseband algorithm development  
5. System performance verification | Hsinchu, Taiwan | 5 years | 1. MS or PhD degree in EE or Communication  
2. Experience in communication system PHY algorithm development  
3. In-depth knowledge on theories and implementations of digital signal processing, channel coding, and communication system  
4. Familiar with commercial wired or wireless communication specifications  
5. Familiar with Matlab and C/C++  
6. Experience in RF/AFE system design, impairment modeling, calibration, mixed-mode system architecture is a plus. | Permanent       |
|               |                          | Senior Physical Design / APR Engineer | 1. Work with Digital Design team for Physical Design of SoC chips including top level floor planning, block partition, timing budgeting, power planning, block integration, whole chip timing closure, and tape out  
2. Responsible for physical design methodology research and development  
3. Cross site projects coordination and management | Hsinchu, Taiwan | 5 years | 1. MS with 5+ years of experience in Physical Design.  
2. Familiar with Unix/Linux environment and scripts  
3. Familiar with ASIC design flow  
5. Good communication and team working skills  
6. Experience in handling large scale SoC chip implementation is a plus | Permanent       |
# 2 job openings from Advanced Analog Technology (台灣類比科技)

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<td>IC Design</td>
<td>台灣類比科技 Advanced Analog Technology (AAT)</td>
<td>Analog IC Design Manager</td>
<td>Responsible for product specification and design supervision</td>
<td>Headquarters 7F-1, No.1, Taiyuan 2nd St., Tai Yuen Hi-Tech Industrial Park, Zhubei City, Hsinchu County 30288, Taiwan, R.O.C. Taipei Branch 3F, No.151, ZhouZi St., Neihu Technology Park, Taipei 11493, Taiwan.</td>
<td>Require 5+ years of analog IC design experiences</td>
<td>1. Require supervisory experience. 2. Require MSEE and 5+ years of analog IC design experiences.</td>
<td>Permanent</td>
</tr>
<tr>
<td>IC Design</td>
<td>台灣類比科技 Advanced Analog Technology (AAT)</td>
<td>R&amp;D Department Head</td>
<td>In charge of the R&amp;D Department and responsible for product design development.</td>
<td>Headquarters 7F-1, No.1, Taiyuan 2nd St., Tai Yuen Hi-Tech Industrial Park, Zhubei City, Hsinchu County 30288, Taiwan, R.O.C. Taipei Branch 3F, No.151, ZhouZi St., Neihu Technology Park, Taipei 11493, Taiwan.</td>
<td>Require 8+ years of analog IC design experiences</td>
<td>1. MSEE or Ph.D. in Electrical Engineering. 2. Require 8+ years of analog IC design experiences.</td>
<td>Permanent</td>
</tr>
</tbody>
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## 2 job openings from Nuvoton Technology Corp. (新唐科技)

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<tr>
<td>IC Design</td>
<td>新唐科技 Nuvoton Technology Corp.</td>
<td>Senior Marketing Director</td>
<td>Build the MCU Product and Marketing Strategy</td>
<td>Hsinchu, San Jose</td>
<td>10 years MCU experience with at least 5 years worked on the MCU marketing</td>
<td>Experience with MCU/MPU Market and Product</td>
<td>Permanent or Contract by 1-year based</td>
</tr>
<tr>
<td>IC Design</td>
<td>新唐科技 Nuvoton Technology Corp.</td>
<td>Senior MCU/MPU Architect</td>
<td>MCU/MPU architecture define</td>
<td>Hsinchu, San Jose</td>
<td>Experience in Tier-1 MCU companies is preferred</td>
<td>Experience with MCU/MPU system architecture and performance requirement</td>
<td>Permanent or Contract by 1-year based</td>
</tr>
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<tr>
<td>IC MFG</td>
<td>華邦電子 Winbond Electronics Corporation</td>
<td>NAND Flash Product (Test) Engineer</td>
<td>With NAND Flash product engineering experience (at least 1 generation PE experience for process development), and 10+ year of product engineering career with strong hands-on bench testing</td>
<td>Hsinchu, Taiwan</td>
<td>10+ year of product engineering career with strong hands-on bench testing</td>
<td>1. Prefer to be willing to work in Taiwan; this is negotiable for outstanding candidates. 2. Expected onboarding date: 2019/Q4</td>
<td>Permanent</td>
</tr>
<tr>
<td>IC MFG</td>
<td>華邦電子 Winbond Electronics Corporation</td>
<td>NAND Flash Process Integration Engineer</td>
<td>NAND Flash technology development</td>
<td>Taichung, Taiwan</td>
<td>With NAND Flash 20nm or 1Xnm process development experience, and at least 10-year of process technology development experiences (or yield enhancement experience)</td>
<td>1. With strong hands-on experience in silicon fabrication processes and integration: lithography, etching, diffusion, thin films deposition. 2. Expected onboarding date: as soon as possible</td>
<td>Permanent</td>
</tr>
<tr>
<td>IC MFG</td>
<td>華邦電子 Winbond Electronics Corporation</td>
<td>NAND Flash Process Module Engineer</td>
<td>NAND Flash technology development 1. Hot Process (Furnace &amp; RTP), LPCVD, ALD, Wet for advanced NOR, 2Xnm beyond NAND flash development. 2. NAND Flash W gate &amp; Air-Gap development. 3. The research experience of CoSi/NiSi material. 4. CVD gap fill and step coverage process control. 5. RRAM TMO new material development.</td>
<td>Taichung, Taiwan</td>
<td>With NAND Flash 20nm or 1Xnm process development experience, and at least 10-year of module process development experiences</td>
<td>With strong hands-on experience in silicon fabrication processes: etching or diffusion</td>
<td>Permanent</td>
</tr>
<tr>
<td>IC MFG</td>
<td>華邦電子 Winbond Electronics Corporation</td>
<td>DRAM Product (Test) Engineer</td>
<td>Evaluation, validation, probe test, yield/quality improvement or failure analysis of DRAMs</td>
<td>Hsinchu, Taiwan</td>
<td>Evaluation, validation, probe test, yield/quality improvement or failure analysis of DRAM(DDR3, DDR4, DDR5, LPDDRs) above 5 years’ experience</td>
<td>1. With DRAM new technology development experience; Experience in DRAM product engineering, DRAM wafer testing engineering, or DRAM product Testing. 2. Familiar with Advantest, MOSAID</td>
<td>Permanent</td>
</tr>
</tbody>
</table>
### Categories
- IC MFG

### Company
- 旺宏電子
- Macronix International

### Job Title
- 3D NAND Advanced Module Process Development Manager

### Job Description
1. **Lithography**: Experience with lithography simulation software and application to state of art high resolution imaging.

2. **Etch**: Strong understanding in principles of plasma dry etch processing, and wet processing and/or chemistry experience in 3D Memory.

3. **Thin Film**: Experience in a variety of thin film deposition techniques, particularly LPCVD/PECVD/ALD/PEALD, PVD, Tungsten and Copper.

4. **Diffusion**: Experience in a variety of Diffusion deposition/oxidation techniques, particularly Diffusion Furnace/Plasma treatment/IPD (ONO) engineering/Polysilicon engineering/Nitride charge trapping/ALD and wet etch/clean.

5. **CMP**: To design, optimize and characterize dielectric and conductive CMP process needed for successful integration processes in 3D Memory.

### Job Location
- Taiwan (Hsinchu Science Park)

### Experiences
- 10 years of experience in semiconductor process development is desired

### Requirements
1. Fundamentals and roles in all processing steps of forming 3D memory devices, peripheral devices and their IC circuit
2. Strong understanding of surface and analytical characterization techniques such as SEM, TEM, CDSEM, XPS, AFM, XRD, AES, EBSD, SIMS etc.
3. Deep understanding of various dielectric/electrical evaluation methods and techniques such as leakage, breakdown, resistance, & on current
4. Experience and/or in-depth knowledge of process ownership and development
5. Interact and collaborate with integration engineers to develop robust unit process and related module as well as transfer the process to production fab
6. Excellent verbal and written communication skill
7. M.S. or PhD in Chemical Engineering, Materials Science, Chemistry or related discipline is required
8. Must have technical expertise within semiconductor processing engineering preferably in 3D Memory process development for leading edge technology

### Position Type
- Permanent
THANK YOU

For job openings and resume submission, please visit